

# **Description**

The HL3063S1 series devices are optocouplers composed of a GaAs infrared light emitting diode and a single-crystal silicon chip random phase photoelectric bidirectional thyristor.

### **Features**

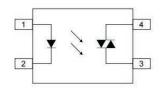
- Peak breakdown voltage
- ELM3053(TA): Min.600V
- 4pin non zero-cross optoisolators triac driver outp
- High input-output isolation voltage(Viso = 3,750Vrms)
- Operating Temperature: -40 ℃~110 ℃
- RoHS

# **Applications**

- Lighting Control
- AC Motor Starter
- Static power switc
- Temperature Controls



SOP-4



Pin Configuration

- 1 Anode
- 2 Cathode
- 3 GND
- 4 VCC

# **Maximum Rating**

Parameter		Symbol	Values	Unit
	Forward Current	ŀ	50	mA
Input	Reverse Voltage	V <sub>R</sub>	6	V
	Power Dissipation	Р	100	MW
	Junction Temperature	T <sub>J</sub>	125	$^{\circ}\mathbb{C}$
Output	Off-State Output Terminal Voltage	$V_{DRM}$	600	V
	On state RMS current	I <sub>T(RMS)</sub>	100	mA(RMS)
	Peak Repetitive Surge Current (PW=1ms,120□pps	I <sub>TSM</sub>	1	А
	Junction Temperature	TJ	125	$^{\circ}\mathbb{C}$
	Collector Power Dissipation	Pc	300	mW
Operating temperature range		T <sub>op</sub>	- 40 <b>~</b> 110	°C
Storage temperature range		T <sub>stg</sub>	- 55 ~ 125	°C
Total Power consumption		P <sub>(W)</sub>	330	mW
Isolation Voltage <sup>(1)</sup>		V <sub>ISO</sub>	3750	Vrms
Soldering Temperature <sup>(2)</sup>		T <sub>SOL</sub>	260	°C

#### Notes:

- (1). AC for 1 minute, R.H.=  $40 \sim 60\%$  R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.
- (2). For 10 seconds



# Electronic Optical Characteristics (TA = 25°C)

	Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditon
Input	Forward Voltage	$V_{F}$	-	1.2	1.6	V	I <sub>F</sub> =10mA
	Reverse Current	I <sub>R</sub>	-	-	5	μΑ	V <sub>R</sub> =6V
	Peak Blocking Current, Either Directiot (1)	I <sub>DRM</sub>	-	-	100	nA	V <sub>DRM</sub> = Rated VDRM
Output	Peak On-State Voltage, Either Dire	$V_{TM}$	-	-	2.5	V	I <sub>TM</sub> =100mA Peak
	Critical rate of Rise of Off-State Voltage (2)	dv/dt	1000	-	-	V/μs	V <sub>in</sub> =240Vrms
Transfer Charact eristics	Led Trigger Current, Current Required to Latch Output,Either Direction	I <sub>FT</sub>	-	-	5	mA	Main Terminal Voltage = 3V
	Holding Current, Either Direction	lΗ	0.5	1.0	5.0	mA	
	Turn-On Time	$T_{on}$	-	-	100	us	$V_D$ =6V R <sub>L</sub> =100 Ω $I_F$ =20mA

<sup>(1)</sup>Test voltage must be applied within dv/dt rating.

<sup>(2)</sup>This is static dv/dt. Commutating dv/dt is a function of the load-driving thyristor(s) only.

### **Characteristics Curves**

Fig.1 Forward current vs.Ambient temperature

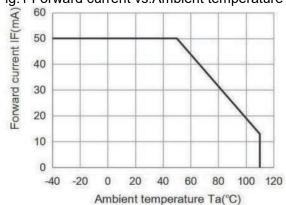


Fig.3 Minimun Trigger Current vs.Ambient temperature

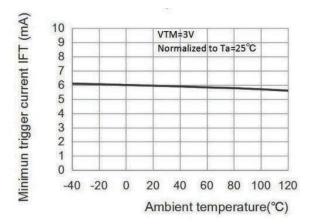


Fig.5 On-state voltage vs . Ambient temperature

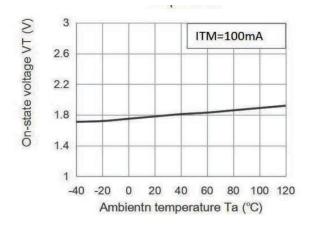


Fig.2 On-state current vs. Ambient temperature

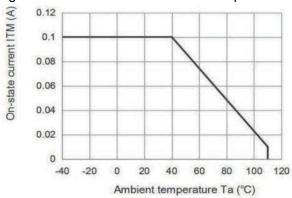


Fig.4 Forward current vs Forward Voltage

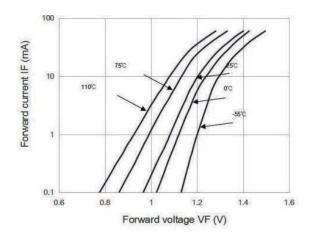


Fig.6 Holding current vs Ambient temperature

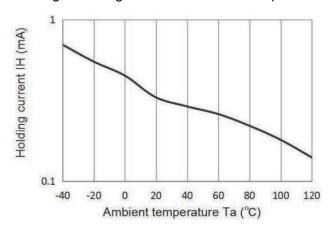


Fig.7 Repetitive peak off-state current vs Temperature

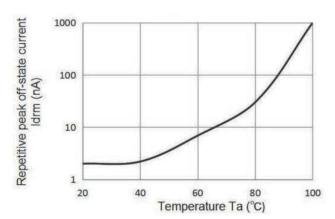


Fig.8 On-state current vs On-state voltage

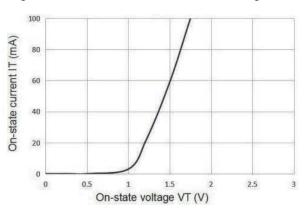


Fig.9 Basic Operation Circuit Medium/High Power Triac Drive Circuit

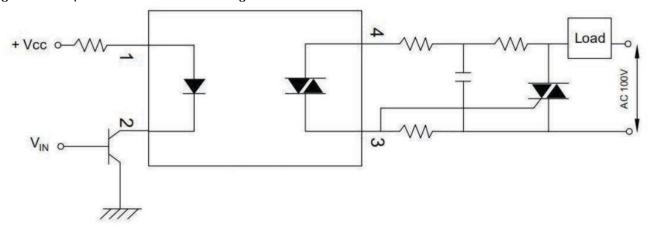
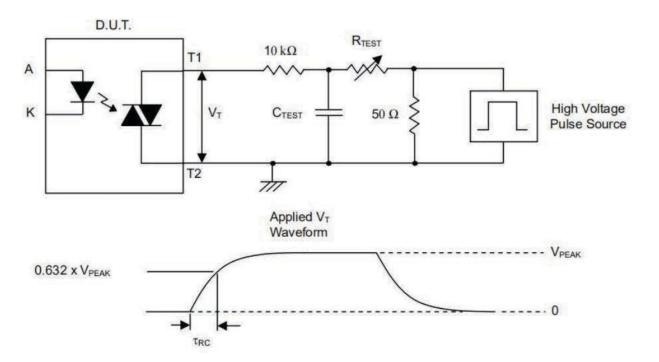
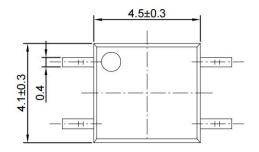
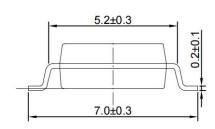


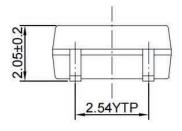
Fig10.Static dv/dt Test Circuit & Waveform



# **Outline Dimension**



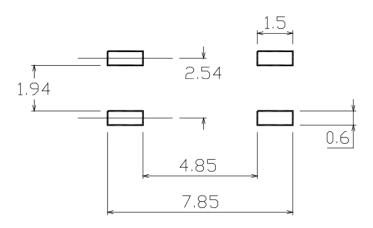




Unit: mm

Tolerance: ±0.1mm

# Recommended solder pad Design



Unit: mm

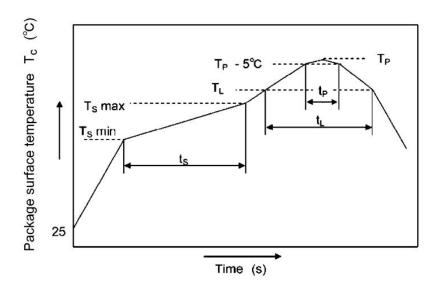
Tolerance: ±0.1mm



# **Temperature Profile Of Soldering**

# 1. IR Reflow soldering (JEDEC-STD-020D compliant)

Profile item	Conditon
Preheat -Temperature Min (TSmin) -Temperature Max (TSmax) -Time (min to max) (ts)	150°C 200°C 90±30 sec
Soldering zone -Temperature (TL) -Time (tL)	217°C 60-150 sec
Peak Temperature (TP) -Time (TP-5℃to TP) (ts) Ramp-up rate	260°C 30sec 3°C / sec max
Ramp-down rate	3~6°C/ sec



## Notes:

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.



## 2. Wave soldering (JEDEC22A111 compliant)

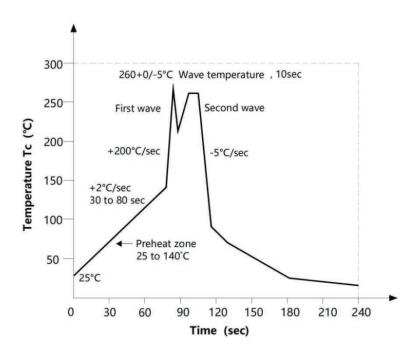
One time soldering is recommended within the condition.

Temperature:260+0/-5°C.

Time:10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



# 3. Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380+0/-5°C

Time: 3 sec max.



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